

COPPER ON ALUMINUM NITRIDE

Thick film copper on aluminum nitride provides excellent electrical conductivity, leach resistance and solderability.

Typical Properties of Copper Metallization System	
Resistivity	2.0 mΩ/sq
Printing Resolution (line/space)	125 μm/125 μm
Wettability (5 sec dip, 62 Sn/36/2 Ag solder)	100%
Adhesion*	≥68.9 MPa

*Pull testing with 3.0 mm square pads and epoxy adhesive aluminum studs.

Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products.

Contact us for applications assistance and fast prototyping.

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425-485-7272
425-485-8651 fax

www.siennatech.com

19501 - 144th Ave. NE, Suite F-500
Woodinville, WA 98072

